

Features

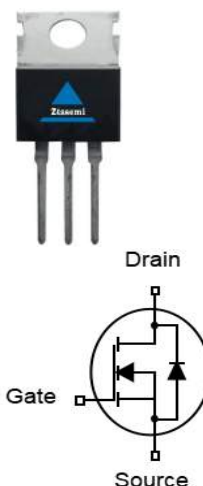
- N-Channel
- Low RDS(ON) & FOM
- Extremely low switching loss
- Excellent reliability and uniformity
- Fast switching and soft recovery
- 100% EAS Tested

V_{DS}	60	V
$R_{DS(on),TYP}@ V_{GS}=10V$	1.6	m Ω
I_D	240	A



Part ID	Package Type	Marking	Packing
ZTG018N06	TO-220	ZTG018N06	1000pcs/Tape

TO-220



Absolute Maximum Ratings $T_A = 25^\circ\text{C}$, unless otherwise specified

Symbol	Parameter	Rating	Unit	
Common Ratings ($T_C=25^\circ\text{C}$ Unless Otherwise Noted)				
V_{GS}	Gate-Source Voltage	± 20	V	
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	60	V	
T_J	Maximum Junction Temperature	150	$^\circ\text{C}$	
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$	
I_{DM}	Drain Current-Continuous@ Current-Pulsed (Note 2)	$T_C = 25^\circ\text{C}$ 960	A	
Mounted on Large Heat Sink				
I_D	Drain Current-Continuous (Note 1)	$T_C = 25^\circ\text{C}$	240	A
		$T_C = 100^\circ\text{C}$	151	A
P_D	Maximum Power Dissipation (Note 3)	184	W	
$R_{\theta JC}$	Thermal Resistance-Junction to Case	0.68	$^\circ\text{C/W}$	
$R_{\theta JA}$	Thermal Resistance Junction-Ambient	62.5	$^\circ\text{C/W}$	
Drain-Source Avalanche Ratings				
EAS	Avalanche Energy, Single Pulsed (Note 6)	870	mJ	

Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Electrical Characteristics @ T_J=25°C (unless otherwise stated)						
V(BR)DSS	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	60	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =60V, V _{GS} =0V	--	--	1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V	--	--	±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	2.5	3	3.5	V
R _{DS(on)}	Drain-Source On-State Resistance	V _{GS} =10V, I _D =50A	--	1.6	2.0	mΩ
Dynamic Electrical Characteristics @ T_J = 25°C (unless otherwise stated) (Note 4,5)						
C _{iss}	Input Capacitance	V _{DS} =30V, V _{GS} =0V, f=1MHz	--	7368	--	pF
C _{oss}	Output Capacitance		--	1653	--	pF
C _{rss}	Reverse Transfer Capacitance		--	48	--	pF
R _g	Gate Resistance	f=1MHz	--	1.4	--	Ω
Q _g	Total Gate Charge	V _{DS} =30V, I _D =50A, V _{GS} =10V	--	104	--	nC
Q _{gs}	Gate-Source Charge		--	40	--	nC
Q _{gd}	Gate-Drain Charge		--	20	--	nC
Switching Characteristics (Note 4,5)						
T _{d(on)}	Turn-on Delay Time	V _{DD} =30V, I _D =50A, R _G =2.5Ω, V _{GS} =10V	--	31	--	ns
T _r	Turn-on Rise Time		--	33	--	ns
T _{d(off)}	Turn-Off Delay Time		--	61	--	ns
T _f	Turn-Off Fall Time		--	16	--	ns
Source- Drain Diode Characteristics @ T_J = 25°C (unless otherwise stated)						
I _S	Diode Forward Current (Note 2)		--	--	240	A
V _{SD}	Forward on voltage (Note 3)	I _S =50A, V _{GS} =0V	--	--	1.4	V
T _{rr}	Reverse Recovery Time	V _R =34V, I _S =50A di/dt=100A/μs	--	72	--	ns
Q _{rr}	Reverse Recovery Charge		--	138	--	nC

Notes:

- The rating only refers to the maximum absolute value of 25 °C in the specification. If the shell temperature is higher than 25 °C, it needs to be derated according to the actual environmental conditions.
- Pulse time 5us, pulse width is limited by the maximum junction temperature.
- The dissipated power value will change with the change of temperature, when greater than 25 °C, the dissipated power value will decrease by 1.47 W/°C with the increase of 1 °C of temperature.
- Pulse test: pulse width ≤ 300μs, Duty Cycle ≤ 2%.
- Basically unaffected by operating temperature.
- EAS condition T_J=25°C, L=0.5mH, V_{DD}=48V, R_G=25Ω,

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

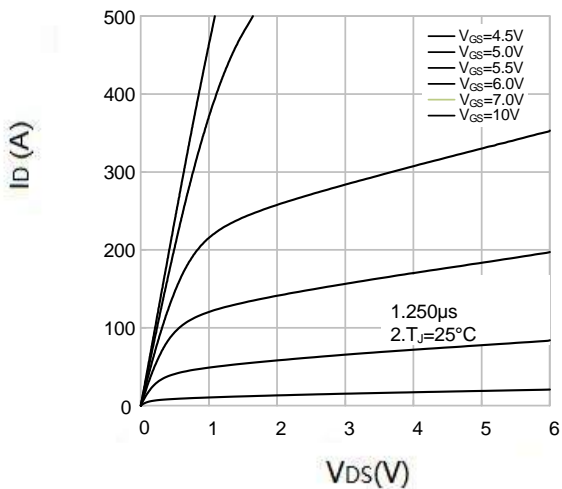


Figure 1 Output Characteristics

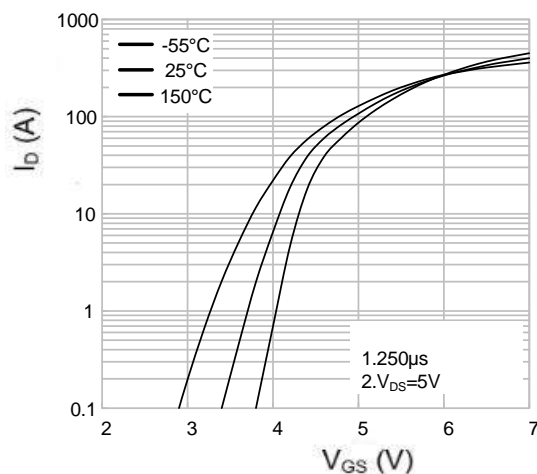


Figure 4 Transfer Characteristics

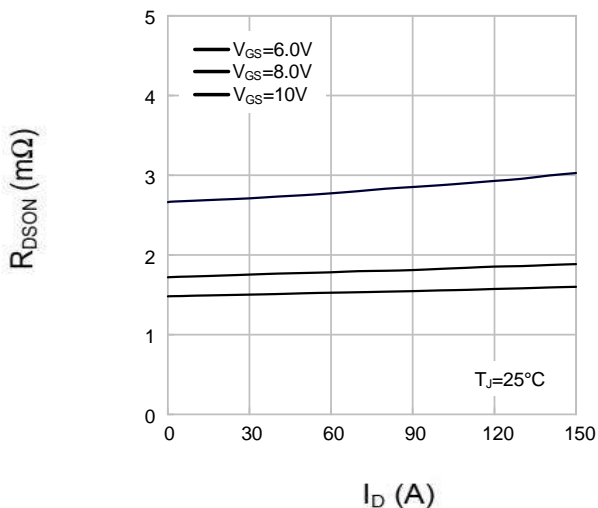


Figure 2 Rds(on)- Drain Current

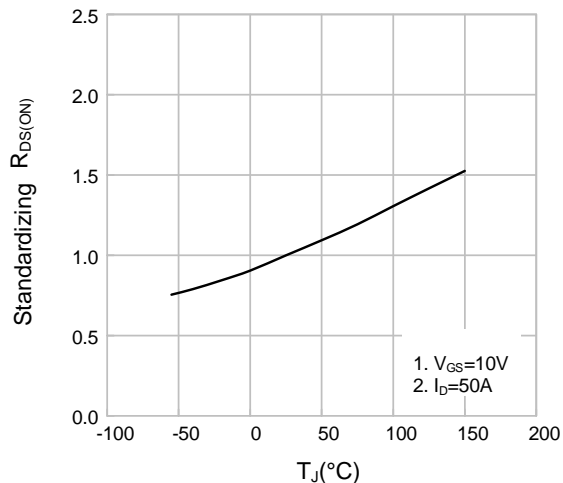


Figure 5 Rds(on) VS Temperature Characteristic

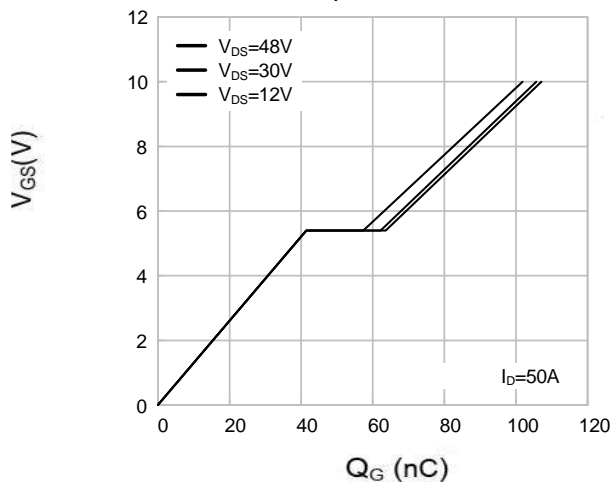


Figure 3 Gate Charge

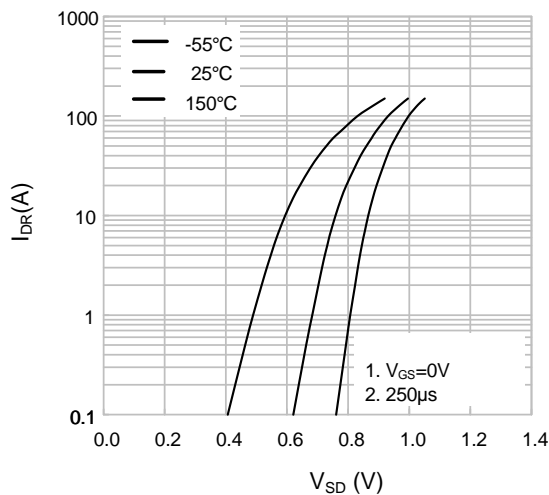


Figure 6 Drain current and temperature - Drain Diode Forward

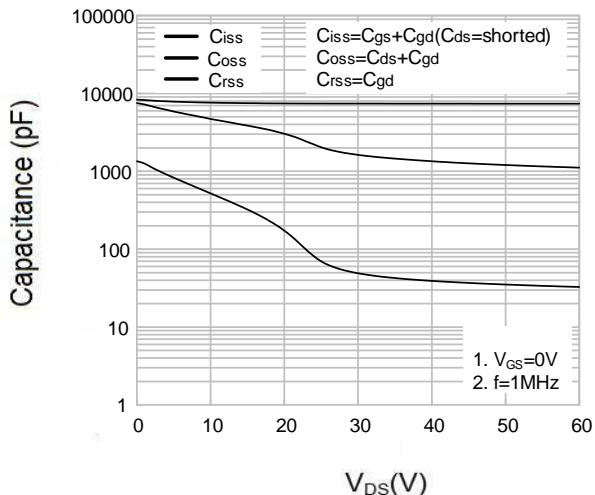


Figure 7 Capacitance vs Vds

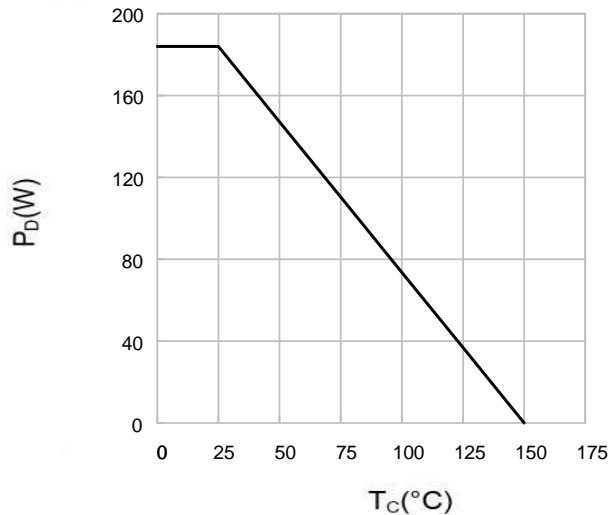


Figure 9 Power De-rating

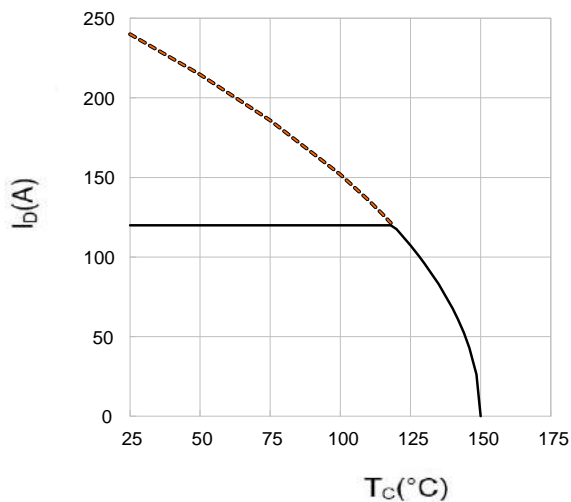


Figure 8 Current De-rating

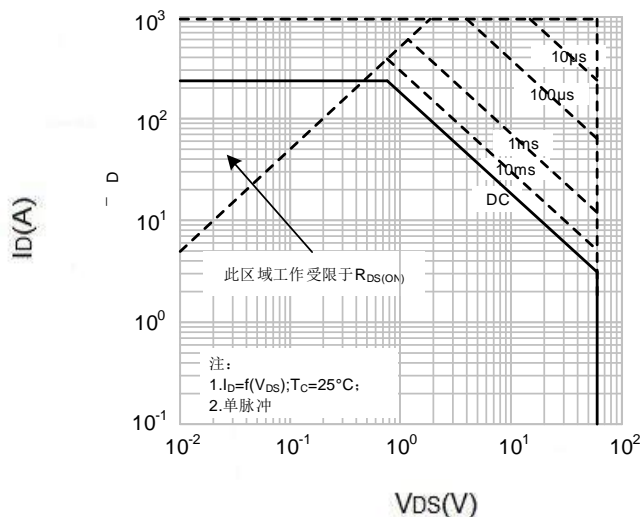


Figure 10 Safe Operation Area

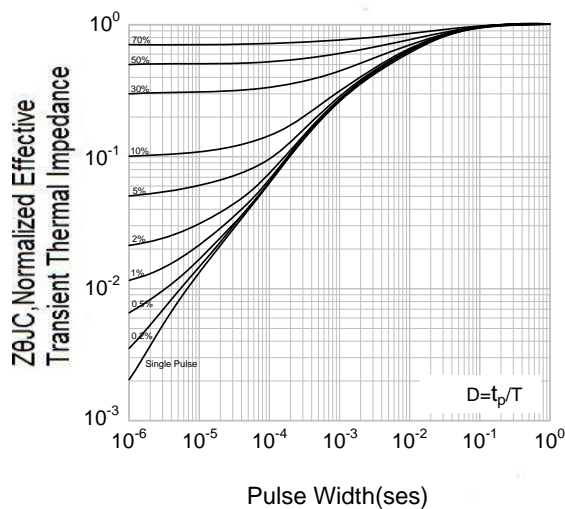
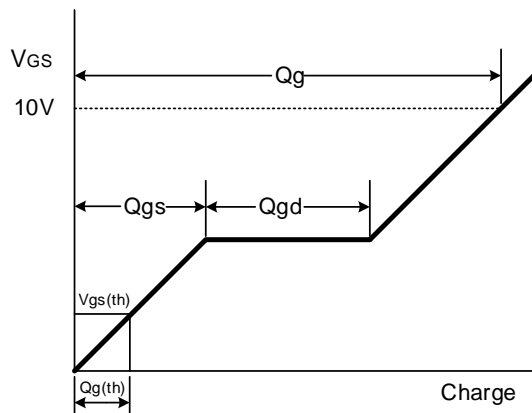
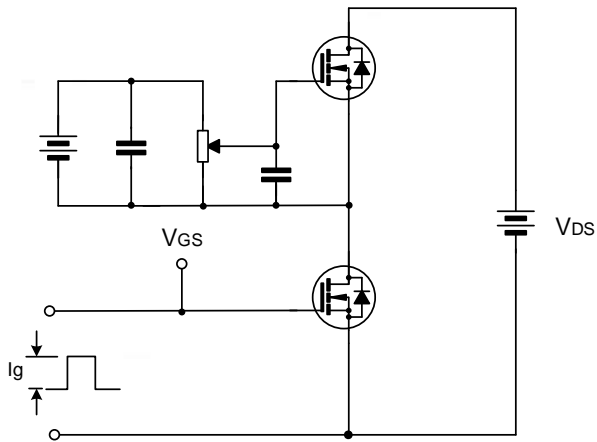


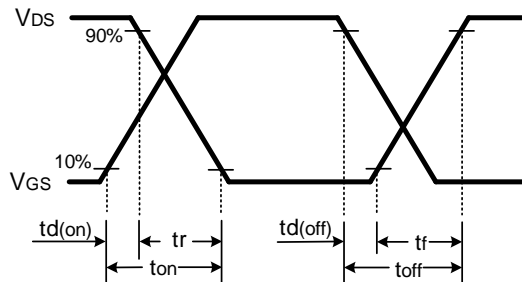
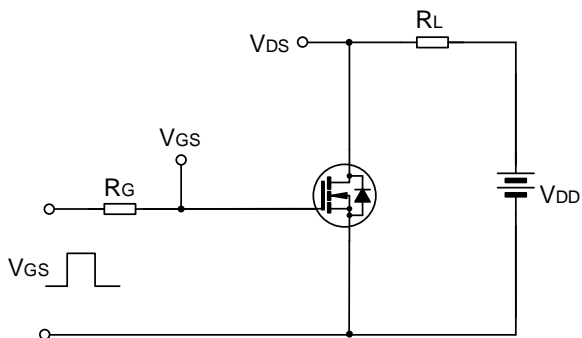
Figure 11 Normalized Maximum Transient Thermal Impedance

Test circuit&Waveform

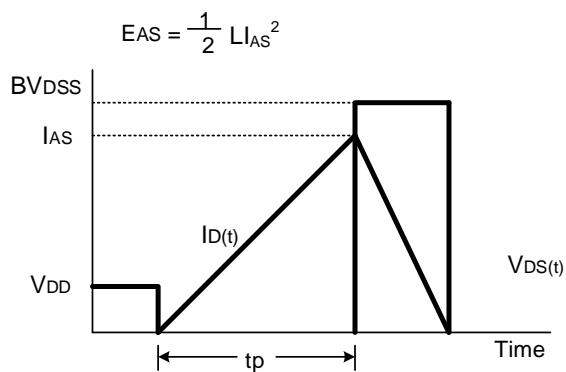
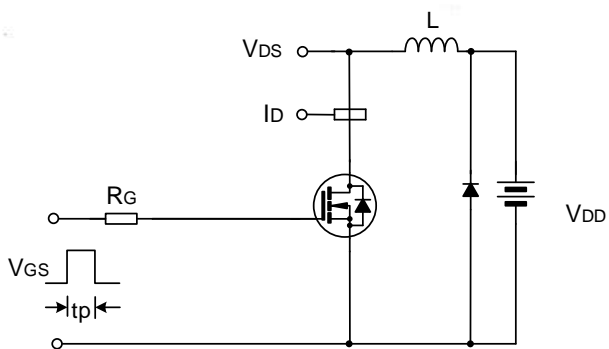
Gate Charge Test Circuit & Waveform



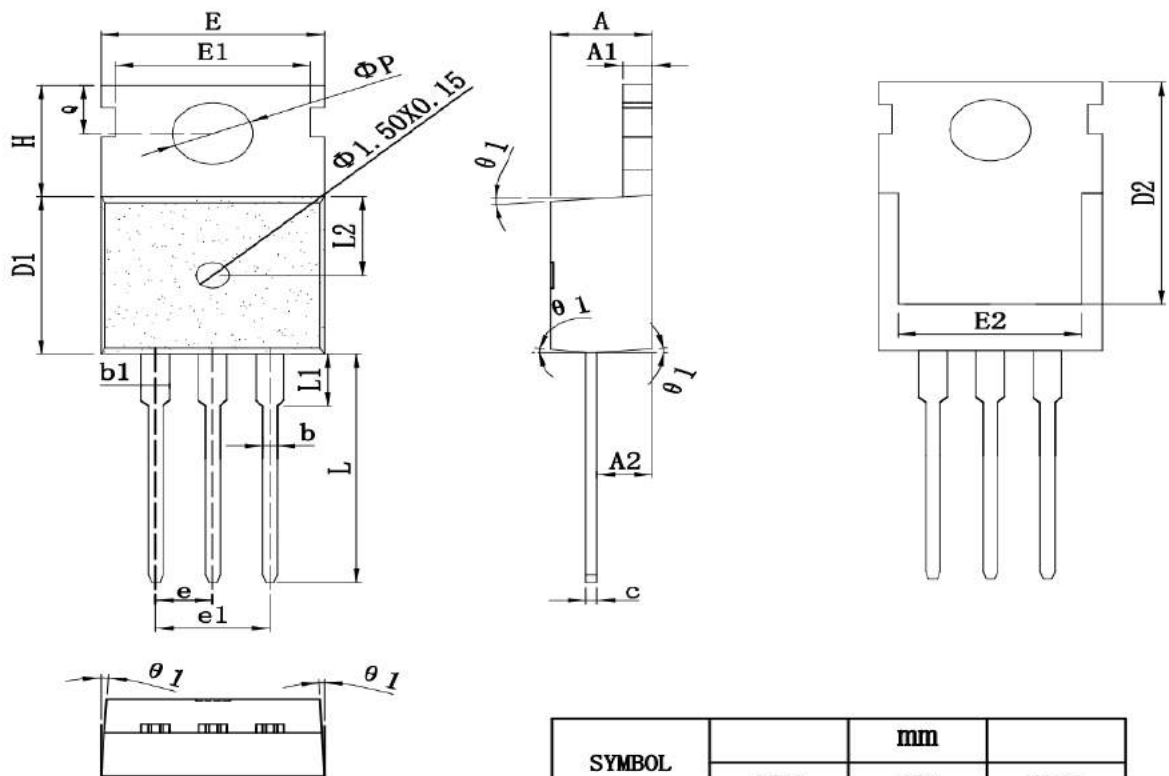
Resistive Switching Test Circuit & Waveforms



EAS Test Circuit & Waveforms



TO-220-3L Package Information



SYMBOL	mm			
	MIN	NOM	MAX	
*A	4.40	4.50	4.60	
*A1	1.25	1.30	1.35	
*A2	2.30	2.40	2.50	
*b	0.75	0.80	0.85	
*b1	1.25	1.33	1.42	
*c	0.45	0.50	0.55	
*D1	9.10	9.20	9.30	
D2	12.90	13.10	13.30	
*E	9.80	10.02	10.15	
*E1	8.55	8.70	8.85	
E2	220FB框架	7.80	8.00	8.20
	220FC框架	7.40	7.60	7.80
*e	2.50	2.54	2.58	
e1	5.08REF			
H	6.40	6.50	6.60	
*L	13.00	13.28	13.45	
*L1	—	—	3.40	
L2	4.55	4.65	4.75	
* ΦP	3.60	3.65	3.75	
*Q	2.70	2.80	2.90	
$\theta 1$	2°	—	7°	

Customer Service

Sales and Service:

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